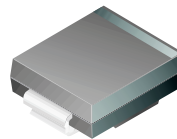




MBRS340

Features

- Compact surface mount with J-bend leads (SMC)
- 3.0 Watt Power Dissipation package
- 3.0 Ampere, forward voltage less than 500 mV



SMC (D0-214AB)
Color Band Denote Cathode
Mark: B34

Schottky Rectifier

Absolute Maximum Ratings*

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Maximum Repetitive Reverse Voltage	40	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_L = 100^\circ\text{C}$ $T_L = 90^\circ\text{C}$	3.0 4.0	A
I_{FSM}	Non-repetitive Peak Forward Surge Current (Half wave, single phase, 60 Hz)	80	A
T_{stg}	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
T_j	Operating Junction Temperature	-65 to +125	$^\circ\text{C}$

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JL}$	Thermal Resistance, Junction to Lead	11	$^\circ\text{C/W}$

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_F	Forward Voltage @ $I_F = 3.0\text{A}$	525	mV
I_R	Reverse Current @ $V_R = 40\text{V}$ $V_R = 40\text{V}, T_A = 100^\circ\text{C}$	2.0 20	mA mA

Typical Characteristics

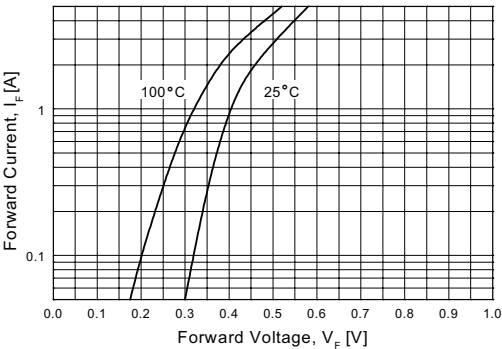


Figure 1. Forward Voltage Characteristics

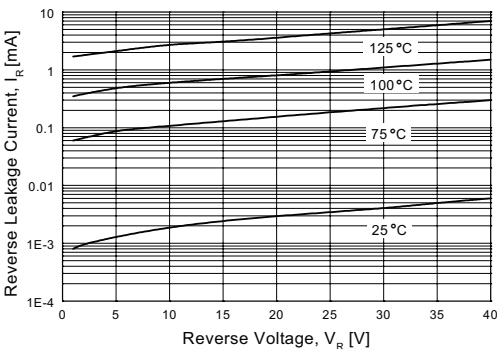


Figure 2. Reverse Current vs Reverse Voltage

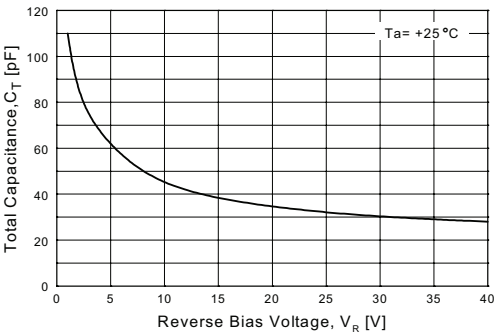


Figure 3. Total Capacitance

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE ^x ™	FAST [®]	OPTOLOGIC™	SMART START™	VCX™
Bottomless™	FAST ^r ™	OPTOPLANAR™	STAR*POWER™	
CoolFET™	FRFET™	PACMAN™	Stealth™	
CROSSVOLT™	GlobalOptoisolator™	POP™	SuperSOT™-3	
DenseTrench™	GTO™	Power247™	SuperSOT™-6	
DOME™	HiSeC™	PowerTrench [®]	SuperSOT™-8	
EcoSPARK™	ISOPLANAR™	QFET™	SyncFET™	
E ² CMOS™	LittleFET™	QS™	TinyLogic™	
EnSigna™	MicroFET™	QT Optoelectronics™	TruTranslation™	
FACT™	MicroPak™	Quiet Series™	UHC™	
FACT Quiet Series™	MICROWIRE™	SILENT SWITCHER [®]	UltraFET [®]	

STAR*POWER is used under license

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

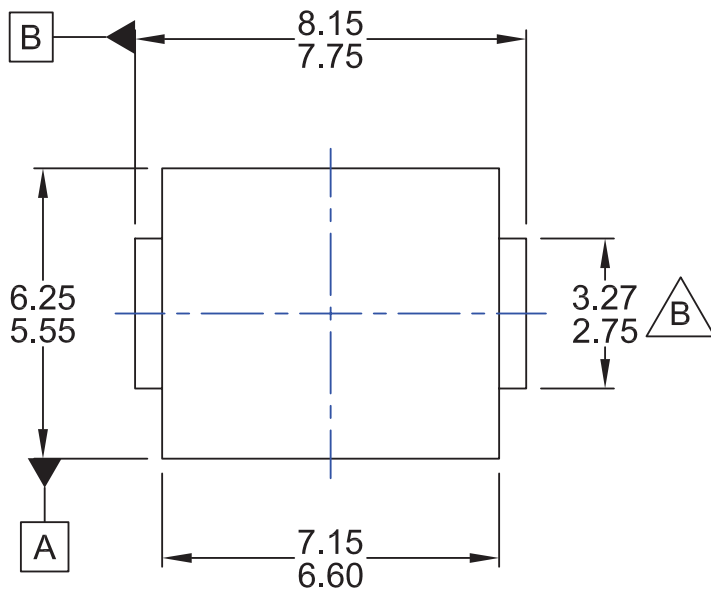
1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

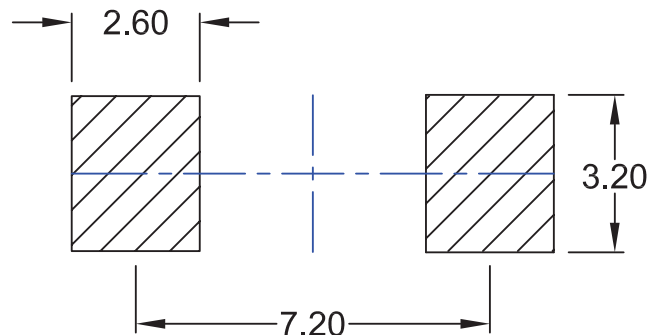
Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

REVISIONS			
LTR	DESCRIPTION	DATE	DRAWN/SITE
1	RELEASE TO DOCUMENT CONTROL	29 APR 08	SD LEE/FSSZ

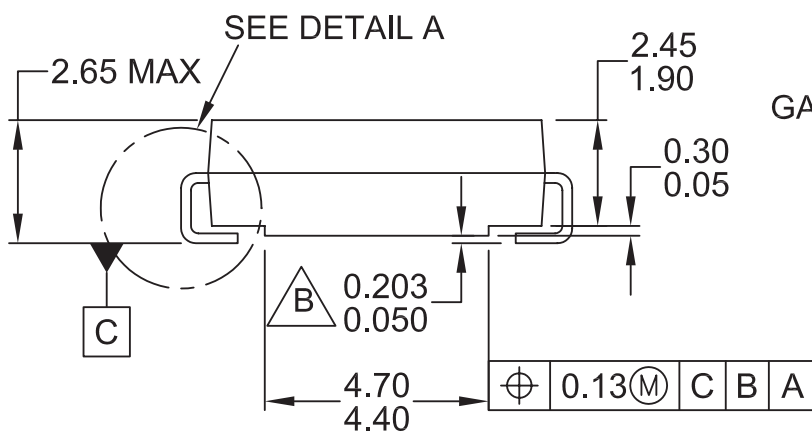


TOP VIEW

\varnothing	0.13	(M)	C	B	A
---------------	------	-----	---	---	---

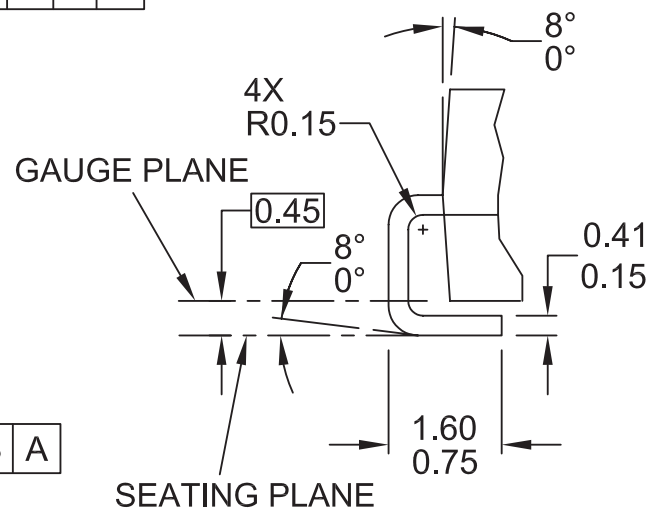


RECOMMENDED LANDPATTERN



SIDE VIEW

\varnothing	0.13	(M)	C	B	A
---------------	------	-----	---	---	---

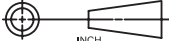


DETAIL A

SCALE: 2:1

NOTES:

- EXCEPT WHERE NOTED CONFORMS TO JEDEC DO-214, VARIATION AB.
- DOES NOT COMPLY TO JEDEC STD. VALUE.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR PROTRUSIONS.
- DIMENSIONS AND TOLERANCING AS PER ASME Y14.5M-1994
- LAND PATTERN STANDARD: DIOM7957X241M
- DRAWING FILE NAME: DO214ABREV1

APPROVALS		DATE		<div><div></div><div>FAIRCHILD</div><div></div><div>SEMICONDUCTOR™</div></div> <div>2LD, SMC, JEDEC</div> <div>DO-214 VARIATION AB</div>			
DRAWN:		BOBOY MALDO				29 APR 08	
CHECKED:		SANGDO LEE					
APPROVED:		LITO GALERA					
HOWARD ALLEN							
<div><div>PROJECTION</div><div></div><div>INCH</div></div>				SCALE	SIZE	DRAWING NUMBER	REV
				1:1	NA	MKT-DO214AB	1
				FORMERLY: N/A			SHEET: 1 OF 1